

STEREO IMPACT

PROBLEM REPORT
PR-1004
SEP LVPS Middle FM1
2004-04-23

PR Numbers: 1xxx=UCB, 2xxx=Caltech/JPL, 3xxx=UMd, 4xxx=GSFC/SEP, 5xxx=GSFC/Mag,
6xxx=CESR, 7xxx=Keil, 8xxx=ESTEC, 9xxx=MPAe

Assembly : SEP LVPS	SubAssembly : Middle Board
Component/Part Number: SEP_Middle_F001	Serial Number: FM1
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Failure Occurred During (Check one)

Functional test Qualification test S/C Integration Launch operations

Environment when failure occurred:

Ambient Vibration Shock Acoustic
 Thermal Vacuum Thermal-Vacuum EMI/EMC

Problem Description

During first power-on of the SEP LVPS Middle Board FM1 the no output was observed at pin 12 of MM54HC123A (one-shot).

Analyses Performed to Determine Cause

The layout is inspected. The capacitor C83 is supposed to be connected only to the Rsat and the Pin 6 of the one-shot. However Pin6 of the one-shot (U26) is also connected to Vcc due to an error in layout generating software.

Corrective Action/ Resolution

Rework Repair Use As Is Scrap

1. Remove C83 (see page 2 of PR-1004 for figures)
2. Remove solder from Pin6 of U26.
3. Using an anti-shock cutter clip Pin 6 of U26 (stake the pad during staking process)
4. Solder a 390pF, 1%, 100V capacitor (CK05) directly onto the chip between pin6 and pin 7 of the one-shot (U26)

Note: Applying 5V to the MM54HC123A at CEXT is not detrimental to the circuit. CEXT can handle maximum of 6V.

Date Action Taken: 4-28-03 **Retest Results:** Success

Corrective Action Required/Performed on other Units Serial Number(s): FM2

Closure Approvals

Subsystem Lead:	_____	Date: _____
IMPACT Project Manager:	_____	Date: _____
IMPACT QA:	_____	Date: _____
NASA IMPACT Instrument Manager:	_____	Date: _____

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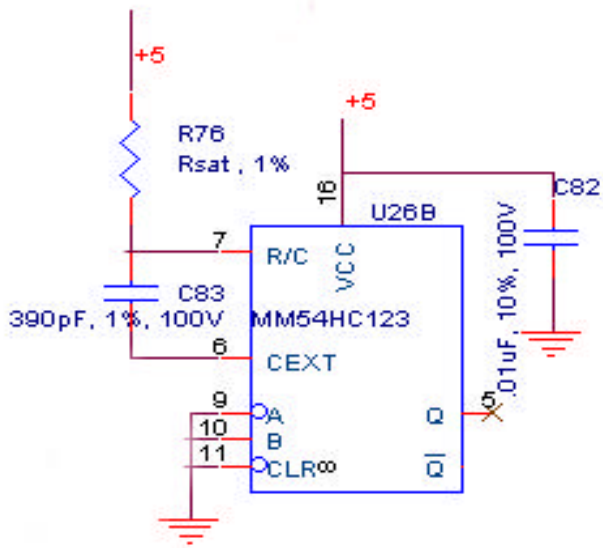


Figure 1: SEP LVPS Middle board Schematic

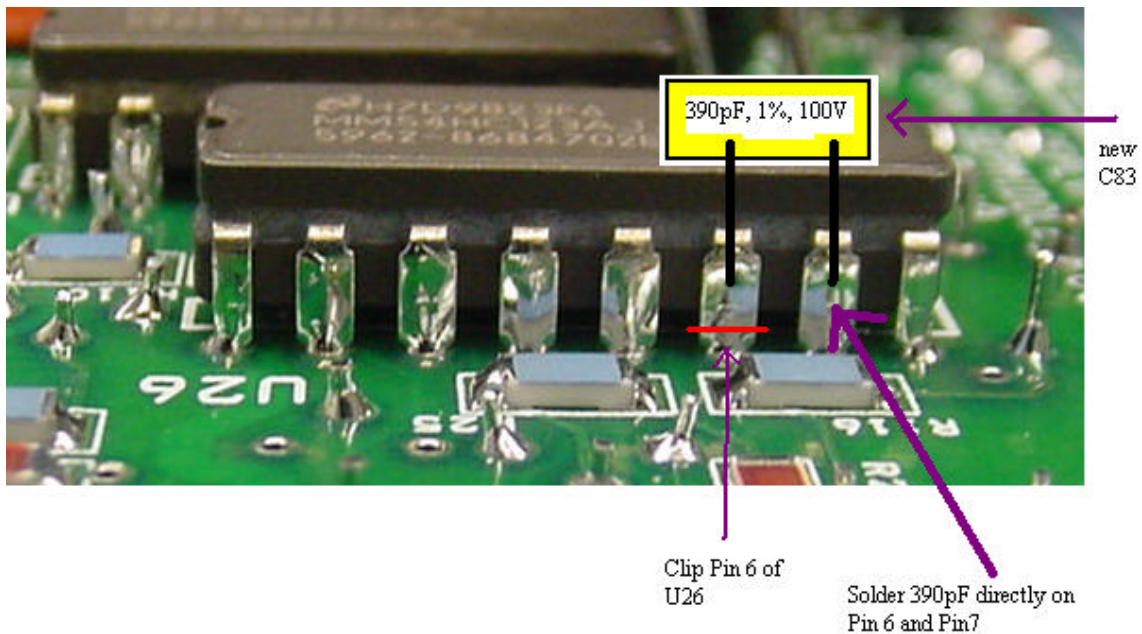


Figure 2: SEP LVPS Middle Board Proposed Solution for PR-1004